

PIN Diode MMIC SP2T Reflective Switch 2-20GHz

Features

PIN Diode SP2T Reflective design

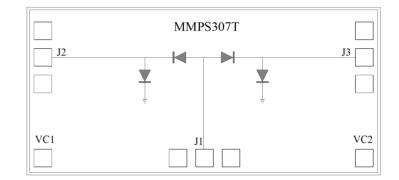
Frequency: 2-20GHz • Isolation: 45dB Typical • Insertion Loss: 0.9 dB Typical • Control Voltage:+5/-5V

• Switching Speed: 20 ns Typical • Die Size: 2.0 x 0.95 x 0.1 mm

Typical Applications

- Voltage control
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

Functional Block Diagram



Electrical Specifications

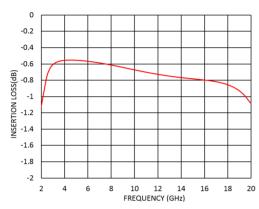
TA = +25°C, VCTL=+5/-5V , +12mA /-10mA Typical

Parameters	Min.	Тур.	Max.	Units
Frequency	2		20	GHz
Insertion Loss		0.8	1.4	dB
Isolation		45		dB
Input Return Loss (ON State)		15		dB
Output Return Loss (OFF State)		15		dB
P1dB - Output 1dB Compression		26		dBm
IIP3-Input Third Order Intercept		43		dBm
Switching Speed		20		ns

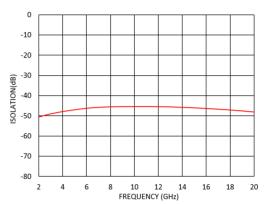


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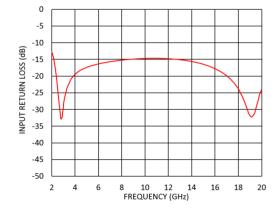
Insertion Loss vs. Frequency



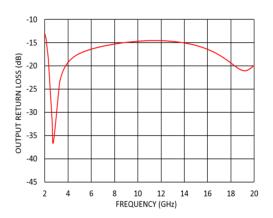
Isolation vs. Frequency



Input Return Loss vs. Frequency



Output Return Loss vs. Frequency





V1.0.0

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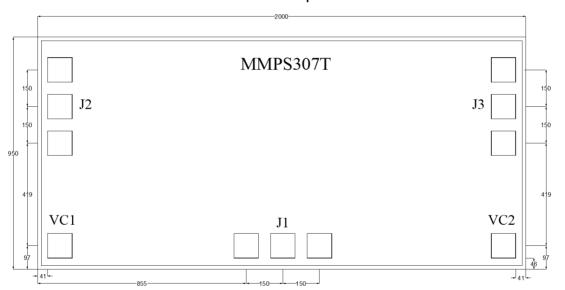
Absolute Maximum Ratings

Max Incident C.W. RF Power	+30dBm
DC Reverse Voltage	25V
Bias Current	±50 mA
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C



Outline Drawing:

All Dimensions in µm



True Table

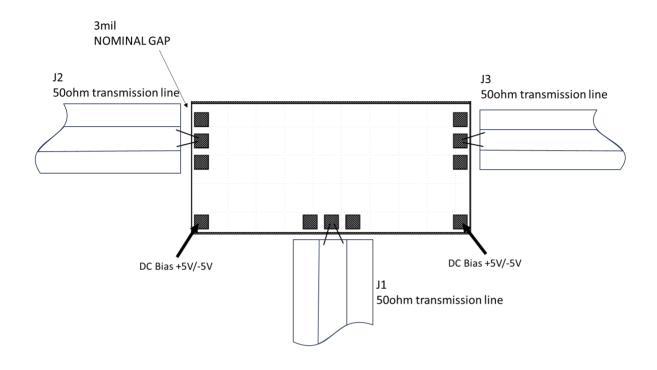
Control Voltage		State	
J2	J3	J2→J1	J3→J1
-5V	+5V	ON	OFF
+5V	-5V	OFF	ON



V1.0.0

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Assembly Drawing



Notes:

1. Die thickness: 100µm

Typical bond pad is 100*100 μm²
Bond pad mentalization: Gold
Backside metallization: Gold
Backside of the die (GND)

6. No connection required for unlabeled bond pads

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